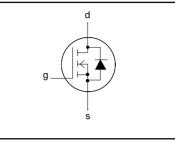
PHP13N40E, PHB13N40E, PHW13N40E

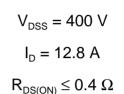
FEATURES

- Repetitive Avalanche Rated
- Fast switching
- Stable off-state characteristics
- High thermal cycling performance
- Low thermal resistance

SYMBOL



QUICK REFERENCE DATA



GENERAL DESCRIPTION

N-channel, enhancement mode field-effect power transistor, intended for use in off-line switched mode power supplies, T.V. and computer monitor power supplies, d.c. to d.c. converters, motor control circuits and general purpose switching applications.

SOT404

tab

2

1

3

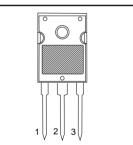
The PHP13N40E is supplied in the SOT78 (TO220AB) conventional leaded package. The PHW13N40E is supplied in the SOT429 (TO247) conventional leaded package. The PHB13N40E is supplied in the SOT404 surface mounting package.

SOT78 (TO220AB)

PINNING

PIN	DESCRIPTION	tab C
1	gate	
2	drain ¹	
3	source	
tab	drain	1 2 3

SOT429 (TO247)



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{DSS} \\ V_{DGR} \\ V_{GS} \\ I_D \\ I_{DM} \\ P_D \\ T_j, T_{stg}$	Drain-source voltage Drain-gate voltage Gate-source voltage Continuous drain current Pulsed drain current Total dissipation Operating junction and storage temperature range	$ \begin{array}{l} T_{j} = 25 \ ^{\circ}C \ to \ 150 \ ^{\circ}C \\ T_{j} = 25 \ ^{\circ}C \ to \ 150 \ ^{\circ}C; \ R_{GS} = 20 \ k\Omega \\ T_{mb} = \ 25 \ ^{\circ}C; \ V_{GS} = 10 \ V \\ T_{mb} = \ 100 \ ^{\circ}C; \ V_{GS} = 10 \ V \\ T_{mb} = \ 25 \ ^{\circ}C \\ T_{mb} = \ 25 \ ^{\circ}C \\ \end{array} $	- - - - - - - - - - 55	$\begin{array}{r} 400\\ 400\\ \pm 30\\ 12.8\\ 8.1\\ 51\\ 156\\ 150\\ \end{array}$	>>> A A A °C

¹ It is not possible to make connection to pin 2 of the SOT404 package.

PHP13N40E, PHB13N40E, PHW13N40E

AVALANCHE ENERGY LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
E _{AS}	Non-repetitive avalanche energy	Unclamped inductive load, $I_D = 12.8 \text{ A}$; $V_{DD} \le 50 \text{ V}$; starting $T_j = 25^{\circ}\text{C}$; $R_{GS} = 50 \Omega$; $V_{GS} = 10 \text{ V}$	-	666	mJ
E _{ar} I _{as} , I _{ar}	Repetitive avalanche energy ² Repetitive and non-repetitive avalanche current		-	16.6 12.8	mJ A

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
	Thermal resistance junction to mounting base		-	-	0.8	K/W
R _{th j-a}	Thermal resistance junction to ambient	SOT78 package, in free air SOT429 package, in free air SOT404 package, pcb mounted, minimum footprint	- -	60 45 50	- -	K/W K/W K/W

ELECTRICAL CHARACTERISTICS

 $T_i = 25$ °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; \text{ I}_{D} = 0.25 \text{ mA}$	400	-	-	V
$\Delta V_{(BR)DSS}$ / ΔT_{j}	Drain-source breakdown voltage temperature coefficient	$V_{DS} = V_{GS}; I_D = 0.25 \text{ mA}$	-	0.1	-	%/K
$\begin{array}{c} R_{DS(ON)} \\ V_{GS(TO)} \\ g_{fs} \end{array}$	Drain-source on resistance Gate threshold voltage Forward transconductance Drain-source leakage current		- 2.0 4	0.35 3.0 8 1	0.4 4.0 - 25	Ω V S μA
I _{DSS} I _{GSS}	Gate-source leakage current	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 320 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 125 \text{ °C}$ $V_{GS} = \pm 30 \text{ V}; V_{DS} = 0 \text{ V}$	-	50 10	500 200	μA μA nA
$\begin{matrix} Q_{g(tot)} \\ Q_{gs} \\ Q_{gd} \end{matrix}$	Total gate charge Gate-source charge Gate-drain (Miller) charge	I_{D} = 12.8 A; V_{DD} = 320 V; V_{GS} = 10 V	-	125 10 68	150 13 85	nC nC nC
$\begin{array}{c} t_{d(on)} \\ t_{r} \\ t_{d(off)} \\ t_{f} \end{array}$	Turn-on delay time Turn-on rise time Turn-off delay time Turn-off fall time	$V_{DD} = 200 \text{ V}; \text{ R}_{D} = 15 \Omega;$ $\text{R}_{G} = 5.6 \Omega$	- - -	18 90 150 100	- - -	ns ns ns ns
L _d L _d	Internal drain inductance Internal drain inductance	Measured from tab to centre of die Measured from drain lead to centre of die (SOT78 package only)	-	3.5 4.5	-	nH nH
L _s	Internal source inductance	Measured from source lead to source bond pad	-	7.5	-	nH
$\begin{array}{c} C_{iss} \\ C_{oss} \\ C_{rss} \end{array}$	Input capacitance Output capacitance Feedback capacitance	$V_{GS} = 0 V; V_{DS} = 25 V; f = 1 MHz$		1400 260 150	-	pF pF pF

 $[\]mathbf{2}$ pulse width and repetition rate limited by T_j max.

PHP13N40E, PHB13N40E, PHW13N40E

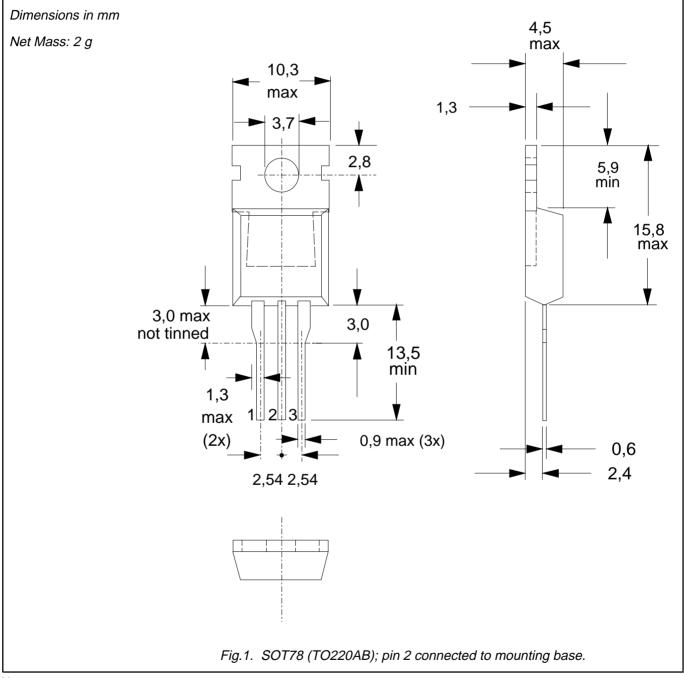
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

 $T_i = 25$ °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
	Continuous source current (body diode)	$T_{mb} = 25^{\circ}C$	-	-	12.8	A
	Pulsed source current (body diode)	$T_{mb} = 25^{\circ}C$	-	-	51	A
V_{SD}	Diode forward voltage	I _s = 12.8 A; V _{Gs} = 0 V	-	-	1.2	V
t _{rr} Q _{rr}	Reverse recovery time Reverse recovery charge	$I_{s} = 12.8 \text{ A}; V_{gs} = 0 \text{ V}; \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$		460 6.7	-	ns μC

PHP13N40E, PHB13N40E, PHW13N40E

MECHANICAL DATA

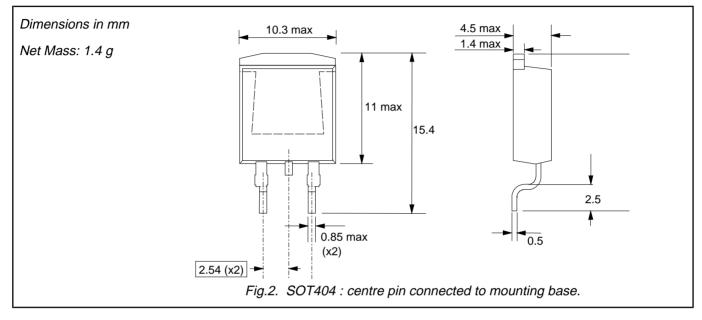


Notes

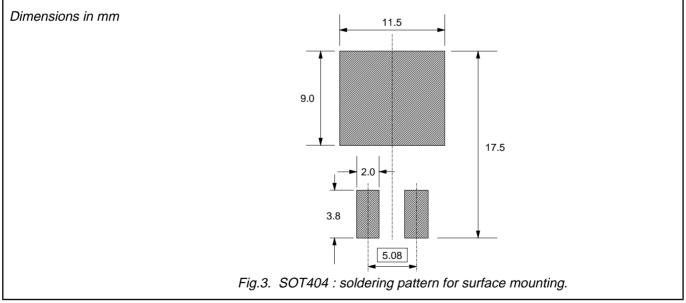
- Observe the general handling precautions for electrostatic-discharge sensitive devices (ESDs) to prevent damage to MOS gate oxide.
 Refer to mounting instructions for SOT78 (TO220) envelopes.
 Epoxy meets UL94 V0 at 1/8".

PHP13N40E, PHB13N40E, PHW13N40E

MECHANICAL DATA



MOUNTING INSTRUCTIONS

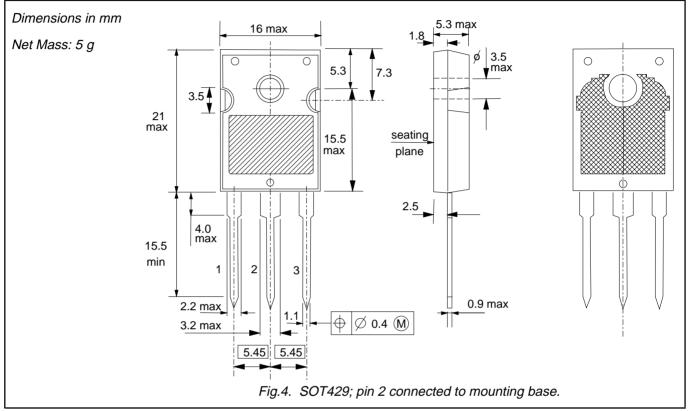


Notes

Observe the general handling precautions for electrostatic-discharge sensitive devices (ESDs) to prevent damage to MOS gate oxide.
 Epoxy meets UL94 V0 at 1/8".

PHP13N40E, PHB13N40E, PHW13N40E

MECHANICAL DATA



Notes

Observe the general handling precautions for electrostatic-discharge sensitive devices (ESDs) to prevent damage to MOS gate oxide.
 Refer to mounting instructions for SOT429 envelope.
 Epoxy meets UL94 V0 at 1/8".

PHP13N40E, PHB13N40E, PHW13N40E

DEFINITIONS

Data sheet status				
Objective specification	This data sheet contains target or goal specifications for product development.			
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.			
Product specification	This data sheet contains final product specifications.			
Limiting values				
Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.				
Application information				
Where application information is given, it is advisory and does not form part of the specification.				
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